

Preliminary Product Information Sheet

(Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.)

MATERIAL ID: EPO-TEK[®] EV2118-2 (formerly 78-118-2)

Date: Jan 2012

Rev: IV

Material Description: A silver-filled, electrically conductive epoxy designed for semiconductor and electronic assembly.

Number of Components: Two

Mix Ratio by Weight: 1:1

Cure Schedule (minimum): 150°C/10 Minutes - 120°C/20 Minutes - 100°C/1 Hour

Specific Gravity: Part A: 2.53 Part B: 3.33

Pot Life: 3 Days

Shelf Life: One year at room temperature

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

MATERIAL CHARACTERISTICS:

PHYSICAL PROPERTIES:

Color (before cure):	Part A: Shiny Silver	Part B: Shiny Silver
Consistency	Smooth Paste	
Viscosity (23°C): @ 100 rpm	2,849 cPs	
Thixotropic Index:	4.4	
Glass Transition Temp:	40 °C	
Shore A Hardness:	55	
Die Shear @ 23°C:	9.3 Kg	
Degradation Temp:	325 °C	
Weight Loss:		
@ 200°C	0.61 %	
@ 250°C	0.84 %	
@ 300°C	1.58 %	
Operating Temp:		
Continuous:	- 55°C to	150 °C
Intermittent:	- 55°C to	250 °C
Storage Modulus:	685,789 psi	
Particle Size:	20 microns	

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	4.03 W/mK
Volume Resistivity @ 23°C:	≤ 0.0005 Ohm-cm

The data above is INITIAL only - it may be changed at anytime, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

*These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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